LOW-PROFILE AND ELEVATED ONE-PIECE

(1.00 mm) .0394" PITCH • A-FSI SERIES

SPECIFICATIONS

Insulator Material:
Liquid Crystal Polymer

Contact Material:
BeCu

Current Rating:
2.8 A per pin
(2 pins powered)

Operating Temp Range:
-55 °C to +125 °C

Plating:
Au over 50 µ" (1.27 µm) Ni

NOTES:

Applications requiring 40-50 positions without threaded inserts, please contact Samtec Interconnect Processing Group.

Some lengths, styles and options are non-standard, non-returnable.

PROCESSING

Lead-Free Solderable:
Yes

SMT Lead Coplanarity:
(0.10 mm) .004" max (05-30)
(0.15 mm) .006" max (50)*
*
(0.004" stencil solution may be available; contact icg@samtec.com)

Compression Board:
Gold Pads required

MOQ Required

No alignment pin
Top side alignment pin
Bottom side alignment pin
Other platings

Table:

<table>
<thead>
<tr>
<th>BODY HEIGHT</th>
<th>A</th>
<th>B</th>
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</thead>
<tbody>
<tr>
<td>–03</td>
<td>(3.00) .118</td>
<td>(8.76) .355</td>
</tr>
<tr>
<td>–06</td>
<td>(6.00) .236</td>
<td>(9.02) .355</td>
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<tr>
<td>–10</td>
<td>(10.00) .394</td>
<td>(9.02) .355</td>
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–L = 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail
–S = 30 µ" (0.76 µm) Gold on contact; Matte Tin on tail

Notes:
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Due to technical progress, all designs, specifications and components are subject to change without notice.

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